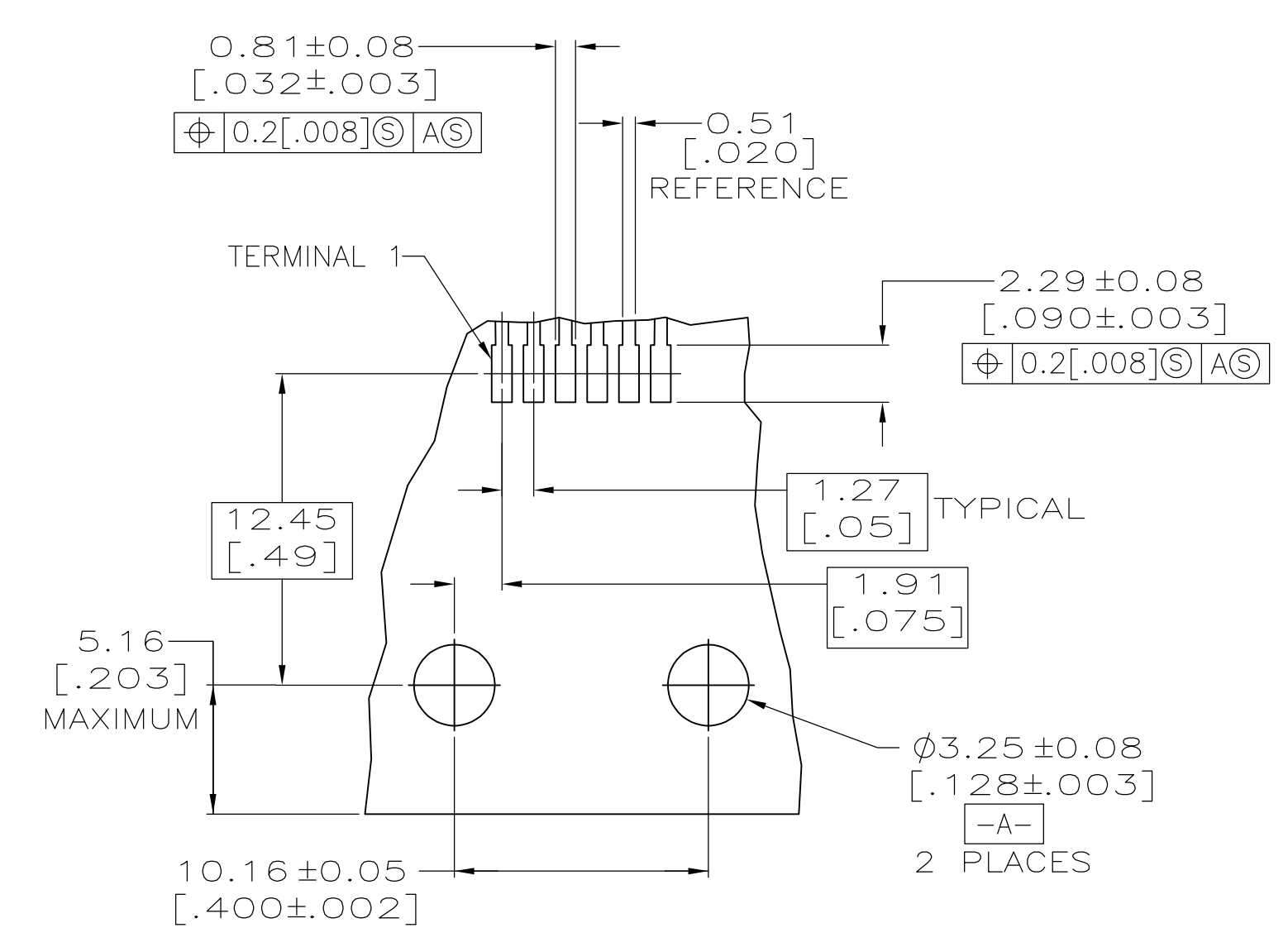
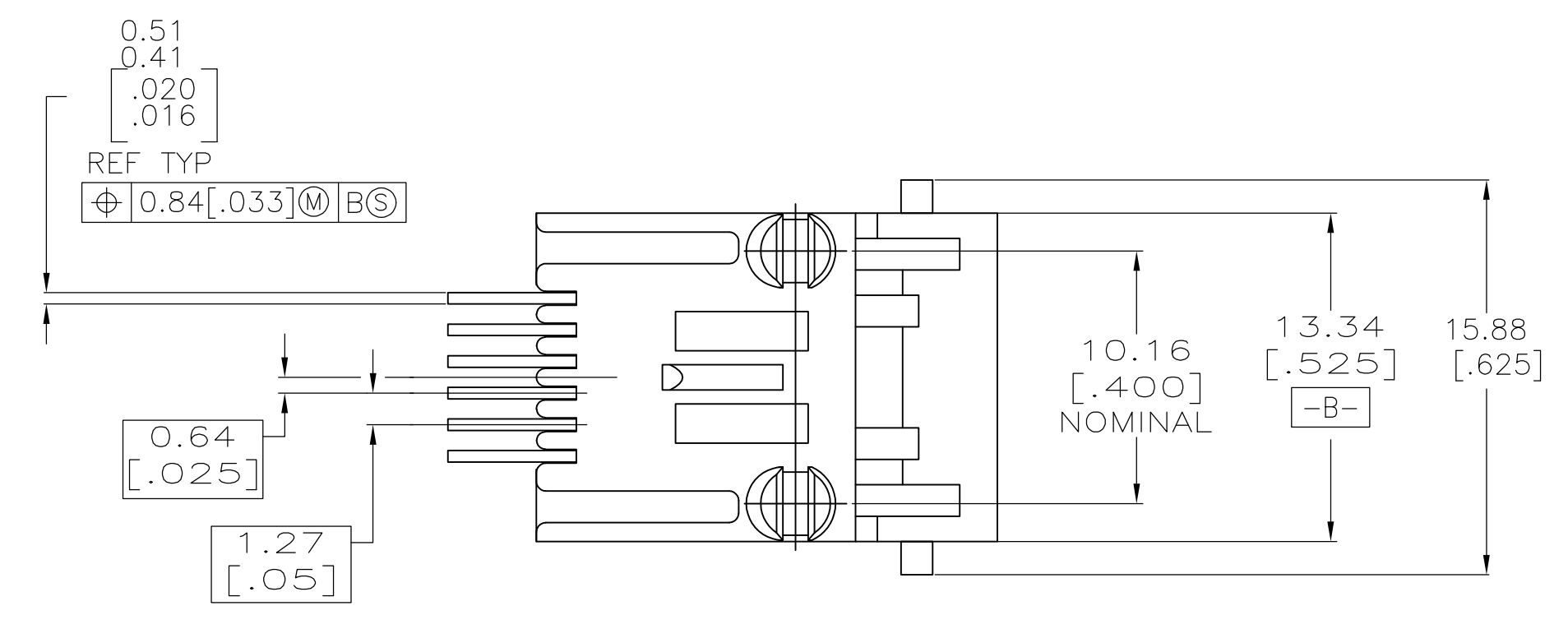
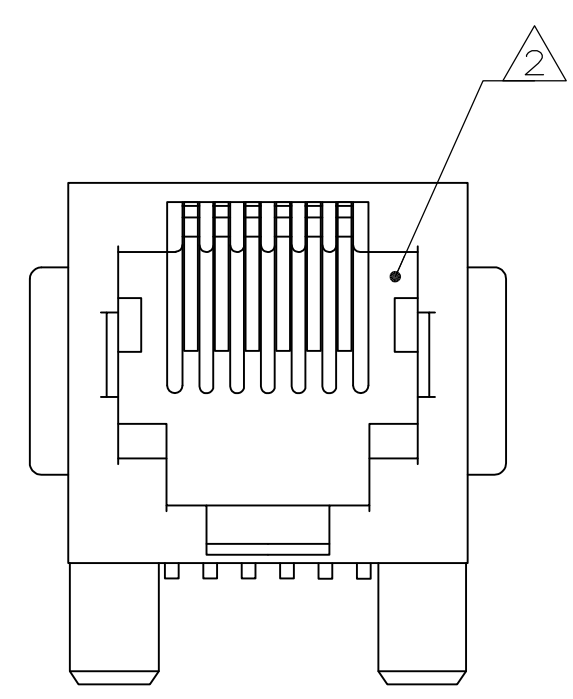
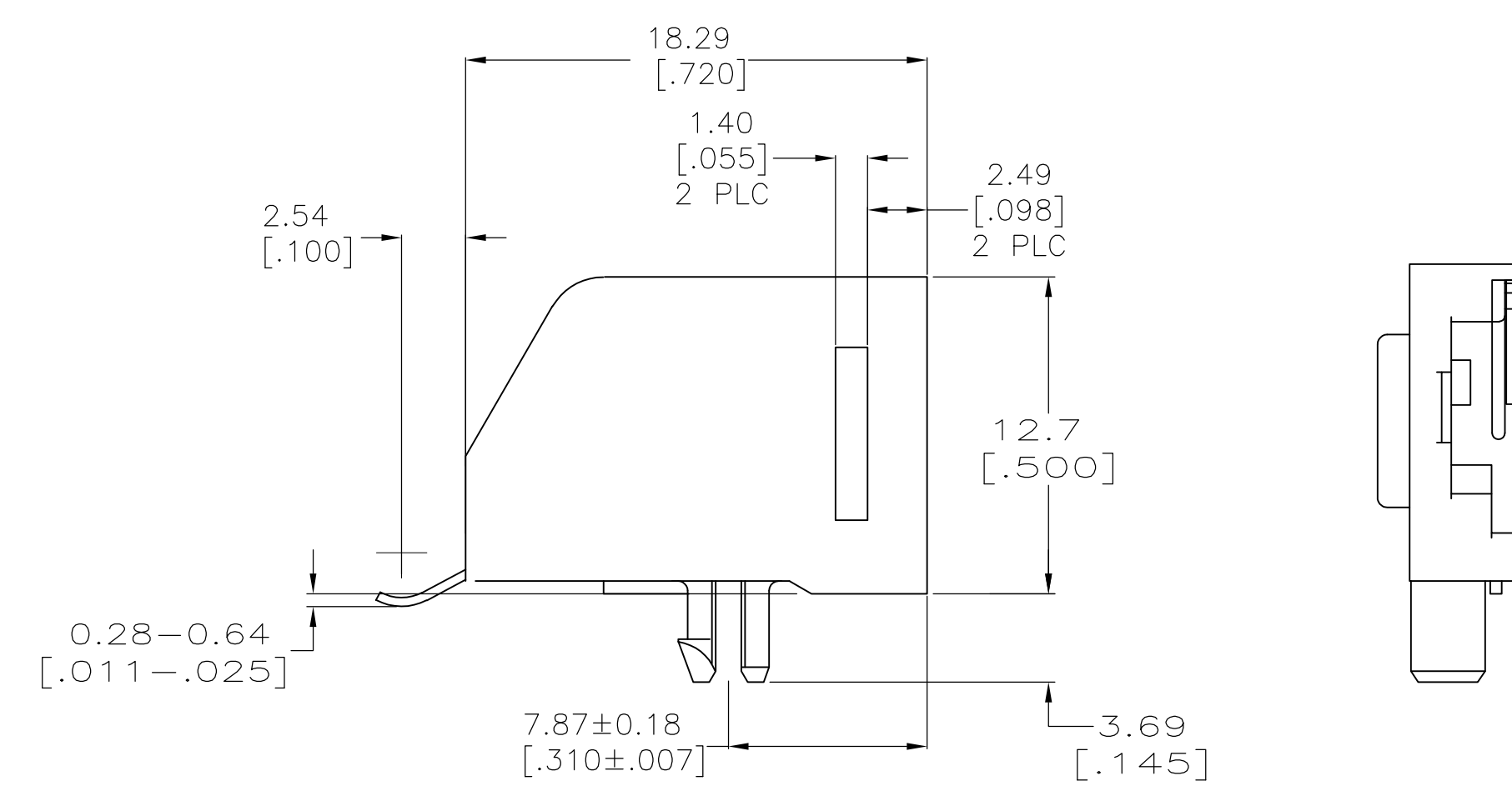
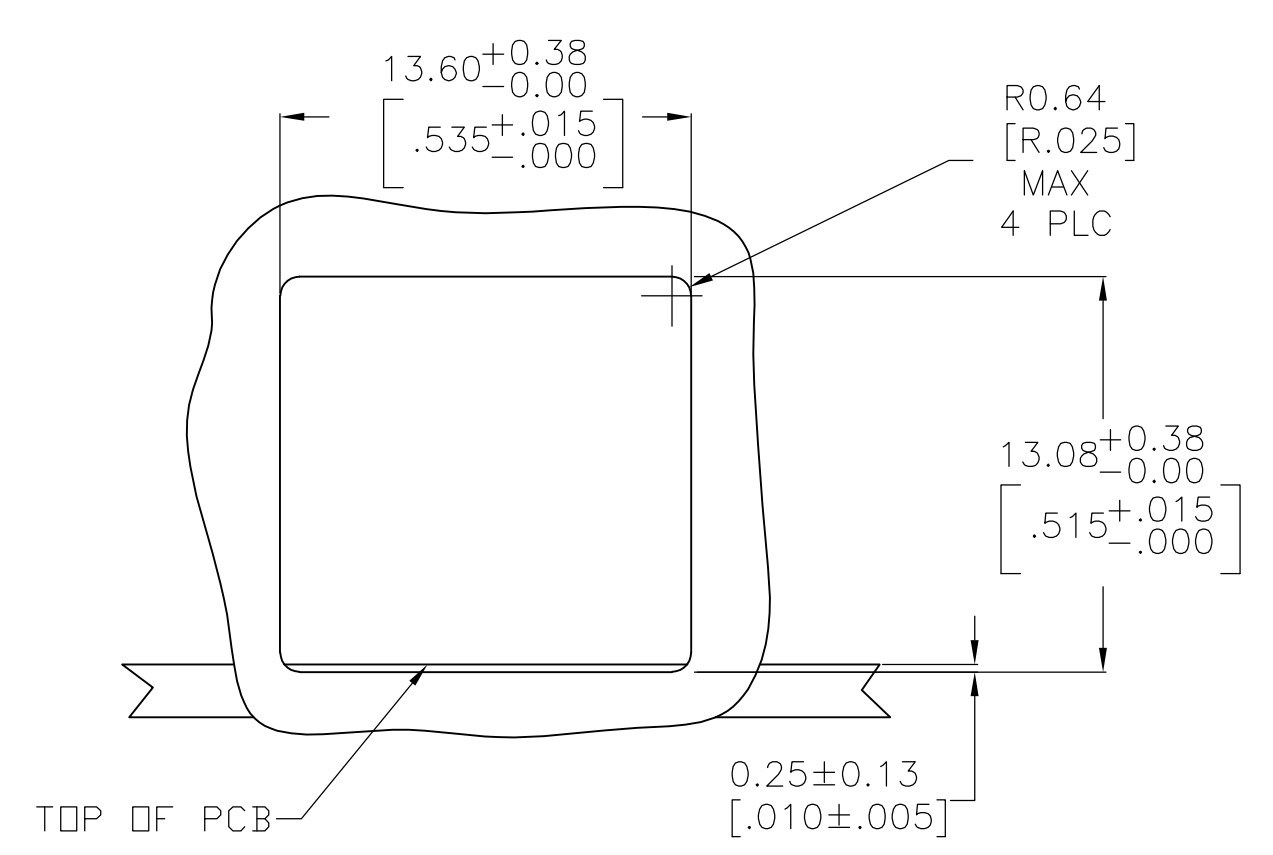


LOC		DIST		REVISIONS			
AA	00	REV	DATE	BY	CHK	APPV	
B1	REVISED PER ECO-11-005033		23MAR11	RK	HMR		



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE



RECOMMENDED PANEL CUTOUT

- MATERIAL: HOUSING- HTN MOLDING COMPOUND, 94VO, COLOR: BLACK.
TERMINAL- 0.36 [.014] THICK PHOS BRONZE PLATED WITH 1.27µm [.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [.000050] MINIMUM THICK NICKEL UNDERPLATE.
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- SNAP-IN RETENTION FEATURE ACCOMMODATES A 1.57±0.13 [.062±.005] THICK PRINTED CIRCUIT BOARD.
- DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
- TERMINALS ASSEMBLED IN CENTER POSITIONS FOR -2.

4 / 5	5555077-2
6	5555077-1
NUMBER OF TERMINALS	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	0 PLC ± -	1 PLC ± -	2 PLC ± -	3 PLC ± -	4 PLC ± -	ANGLES ± -
SEE NOTE 1	SEE NOTE 1	CUSTOMER DRAWING					

DWG: G. ATTADIA - 07JUN2005	CHK: J. WESTMAN - 07JUN2005	APPV: S. FLICKINGER - 07JUN2005	NAME: MODULAR JACK ASSEMBLY, 6 POSITION, LOW PROFILE, RIGHT ANGLE, SURFACE MOUNT W/ PANEL STOPS
SIZE: A1	CAGE CODE: 100779	DRAWING NO: 5555077	RESTRICTED TO: -
SCALE: 4:1	SHEET: 1 OF 1	REV: B1	

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)